

MEI

SURFACE MOUNT GLASS PASSIVATED RECTIFIER

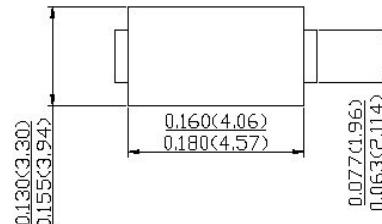
S1AB THRU S1MB

VOLTAGE RANGE 50 to 1000 Volts
CURRENT 1.0 Ampere

FEATURES

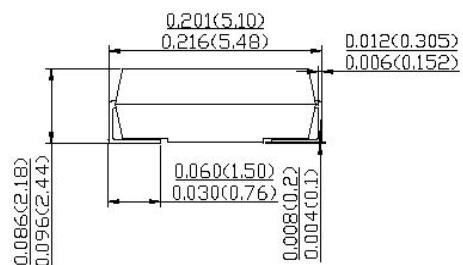
- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- For surface mounted applications
- Low profile package
- Built-in strain relief, ideal for automated placement
- Glass Passivated chip junction
- High temperature soldering:
260 degree C/10 seconds, 265 degree C /5 seconds at terminals.

SMB



MECHANICAL DATA

- Case: JEDEC DO-214AC molded plastic over glass passivated chip
- Terminals: Solder plated, solderable per MIL - STD - 750, Method 2026
- Polarity: Color band denotes cathode end
- Weight: 0.002 ounce, 0.064 gram



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

- Ratings at 25°C ambient temperature unless otherwise specified

Dimensions in inches and (millimeters)

Maximum Ratings & Thermal Characteristics

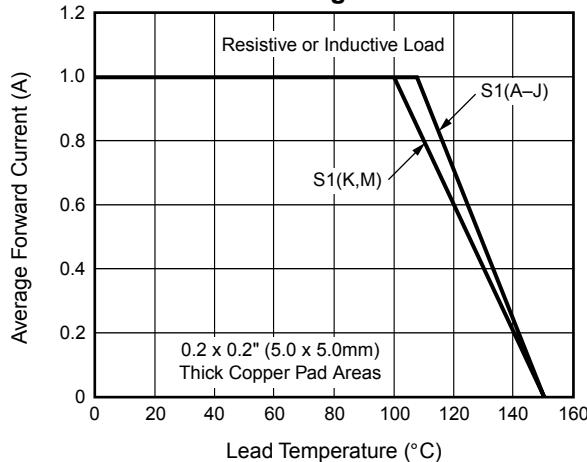
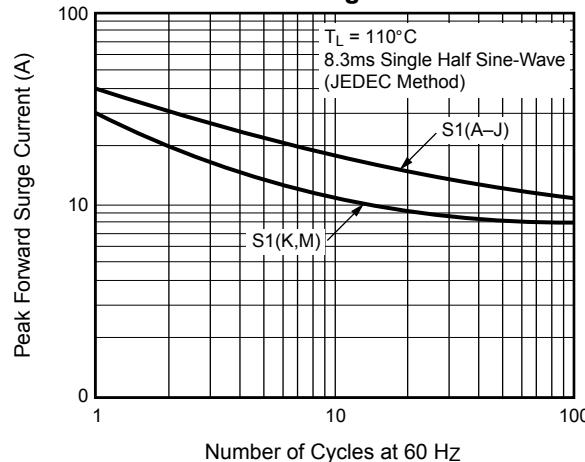
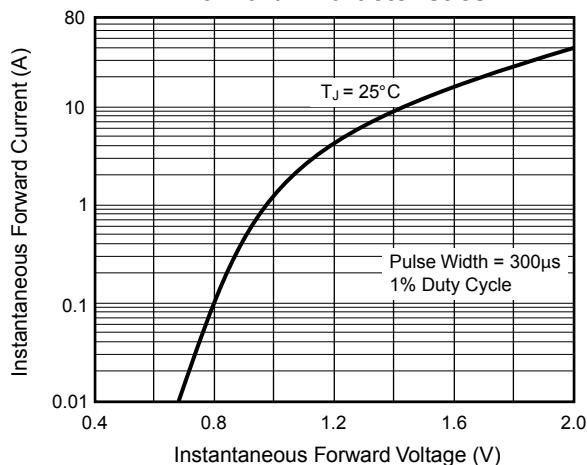
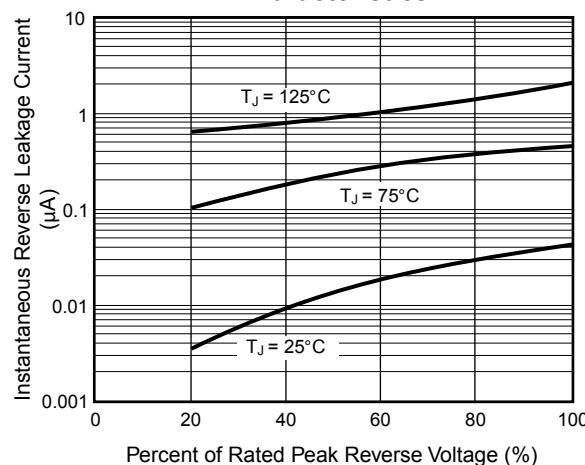
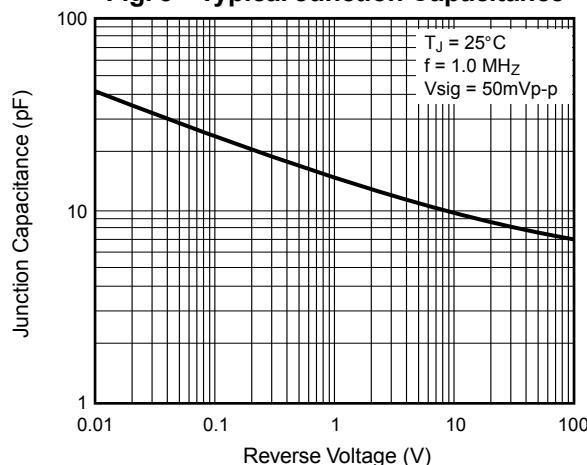
Parameter	Symbol	S1AB	S1BB	S1DB	S1GB	S1JB	S1KB	S1MB	Unit
Maximum recurrent peak reverse voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current (see fig. 1)	I _{F(AV)}				1.0				A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method) T _L =110°C	I _{FSM}			40			30		A
Typical thermal resistance (NOTE 1)	R _{θJA}			75		85			°C/W
	R _{θJL}			27		30			
Operating junction and storage temperature range	T _J , T _{TSG}			−55 to +150					°C

Electrical Characteristics Ratings at 25°C ambient temperature unless otherwise specified.

Parameter	Symbol	S1AB	S1BB	S1DB	S1GB	S1JB	S1KB	S1MB	Unit
Maximum instantaneous forward voltage at 1.0A	V _F			1.10					V
Maximum DC reverse current at Rated DC blocking voltage	I _R			1.0		5.0			μA
				50					
Typical reverse recovery time at I _F = 0.5A, I _R = 1.0A, I _{rr} = 0.25A	t _{rr}			1.8					μs
Typical junction capacitance at 4.0V, 1MHz	C _J			12					pF

Note: (1) Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.2 x 0.2" (5.0 x 5.0mm) copper pad areas

RATINGS AND CHARACTERISTIC CURVES S1AB THRU S1MB

Fig. 1 – Forward Current Derating Curve**Fig. 2 – Maximum Non-Repetitive Peak Forward Surge Current****Fig. 3 – Typical Instantaneous Forward Characteristics****Fig. 4 – Typical Reverse Leakage Characteristics****Fig. 5 – Typical Junction Capacitance****Fig. 6 – Transient Thermal Impedance**